Preface

We are pleased to present the proceedings from the 4th International Conference on Mechanical Structures and Smart Materials (ICMSSM), which was held on September 22-23, 2018 in Shenzhen, China.

The aim of ICMSSM2018 was to bring together experts from the academia and industry to present and discuss their research results and development in the areas of mechanical structures and smart materials. It provided opportunities for delegates to exchange new ideas and application experiences, and to establish collaborations. The scientific programme was highly engaging and featured some very high impact presentations. Undoubtedly, some of the research presented would contribute significantly to the knowledge in the respective field of studies. The proceedings presented here comprise a selection of papers that were selected on the basis of originality, significance and relevance to the conference theme.

We would like to thank all the authors who have contributed to this volume and also to the speakers, reviewers, chairpersons, organising committee and all participants for their support to ICMSSM2018.

November 2018

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